

**NOTE:**

**1.MATERIAL:**

**HOUSING: HIGH TEMPERATURE THERMOPLASTIC.**

**CONTACT: COPPER ALLOY.**

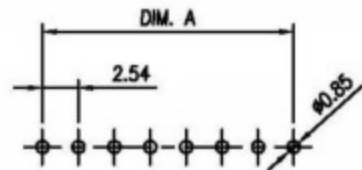
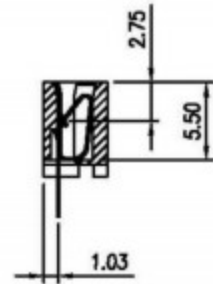
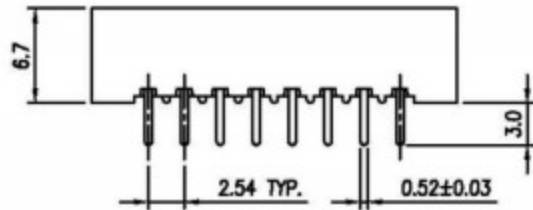
**2.FINISH:**

**TERMINAL:**

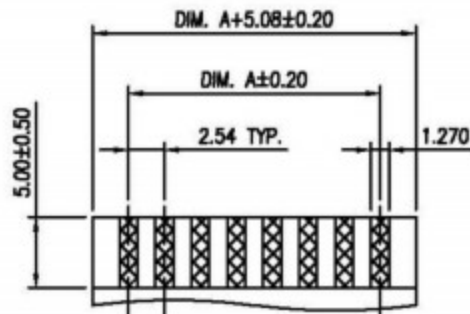
**CONTACT AREA: TIN PLATING 100 μ" THICKNESS MIN.**

**SOLDERING AREA: TIN PLATING 100 μ" THICKNESS MIN.;**

**UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN. OVERALL.**



RECOMMENDED PCB LAYOUT  
TOLERANCES: ±0.05



FPC/FFC T=0.30±0.05

**DIMENSION TABLE**

Pos.	Dimension			Pos.	Dimension C		
	A	B	C		A	B	C
2	2.54	8.43	10.54	15	35.56	41.45	43.56
3	5.08	10.97	13.08	16	38.10	43.99	46.10
4	7.62	13.51	15.62	17	40.64	46.53	48.64
5	10.16	16.05	18.16	18	43.18	49.07	51.18
6	12.70	18.59	20.70	19	45.72	51.61	53.72
7	15.24	21.13	23.24	20	48.26	54.15	56.26
8	17.78	23.67	25.78	21	50.80	56.69	58.80
9	20.32	26.21	28.32	22	53.34	59.23	61.34
10	22.86	28.75	30.86	23	55.88	61.77	63.88
11	25.40	31.29	33.40	24	58.42	64.31	66.42
12	27.94	33.83	35.94	25	60.96	66.85	68.96
13	30.48	36.37	38.48	26	63.50	69.39	71.50
14	33.02	38.91	41.02				

**Test Requirements and Procedures Summary**

Test Item	Requirement	Procedure
1 Examination of Product	Meets requirements of product drawing. No physical damage.	Visual inspection.
<b>ELECTRICAL REQUIREMENT</b>		
2 Contact Resistance	[30] m Ohm Max(Initial) [50] m Ohm Max(Final)	Subject mated contacts assembled in housing to 20mV Max open circuit at 10mA Max. EIA-364-6B.
3 Dielectric withstanding Voltage	No creeping discharge or flashover shall occur. Current leakage: 0.5 mA MAX	[500]VAC for 1minute Test between adjacent circuits of unmated connector. EIA-364-20B
4 Insulation Resistance	[500] M Ohm Min.(Initial)	Impressed voltage 500 VDC. Test between adjacent circuits of unmated connector. EIA-364-21C.
<b>MECHANICAL REQUIREMENT</b>		
5 Insertion Force	150 gram/Pin Max.	Operation Speed : [25] mm/min. Measure the force required to mate connector. EIA-364-13B
6 Withdrawal Force	40 gram/Pin Min.	Operation Speed : [ 25] mm/min. Measure the force required to unmate connector. EIA-364-13B
7 Durability	No defects.	Operation Speed : [ 25 ] mm/min. 20 Cycles Durability Cycles : EIA-364-9C
8 Contact Retention Force	0.3 kg Min.	Measure the contact retention force with Tensile strength tester.
9 Solder ability	Wet solder coverage : 95% Min.	Solder Temperature : 245±5°C Duration : 5±1 sec, J-STD-002B
<b>ENVIRONMENTAL REQUIREMENTS</b>		
10 Resistance to Wave Soldering Heat	No physical damage shall occur. (Lead-Free)	Solder Temp. : 250±5°C, 10±0.5sec.
11 Humidity	Appearance: No damage Contact resistance: Less than twice of initial Voltage resistance: No spark or insulation damage occur	40 ± 2°C, 90-95%RH, 96hours measurement must be taken within 30 min. after tested.
12 Heat aging	Contact resistance: Less than twice of initial	85 ± 2°C , 96 hours
13 Salt Spray	No detrimental corrosion allowed in contact area and base metal exposed.	Subject mated connectors to 35±2 °C and 5±1% salt condition for 8 hours. After test, rinse the sample with water and recondition the room temperature for 1 hour. EIA-364-26B.